BR2SK3018WQ

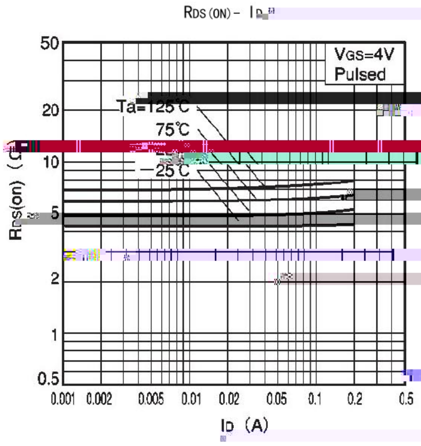
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	±20	V
Drain Current – Continuous	I_D	100	mA
Drain Current– Pulsed	I_{DP}^{*1}	200	mA
Reverse drain current–Continuous	I_{DR}	100	mA
Reverse drain current– Pulsed	I_{DRP}^{*1}	200	mA
Total power dissipation (T_c=25)	P_D^{*2}	200	mW
Channel Temperature	T_{ch}	150	V
Storage Temperature Range	T_{stg}	-55 150	

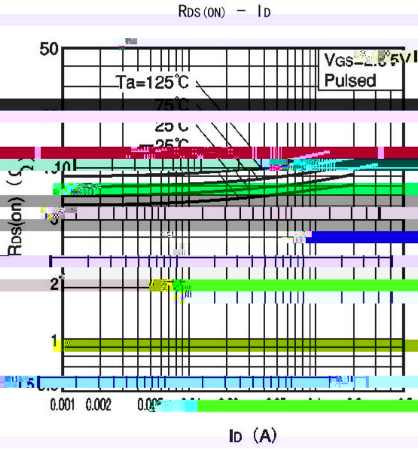
*1:Pw≤10μs, Duty cycle≤50%

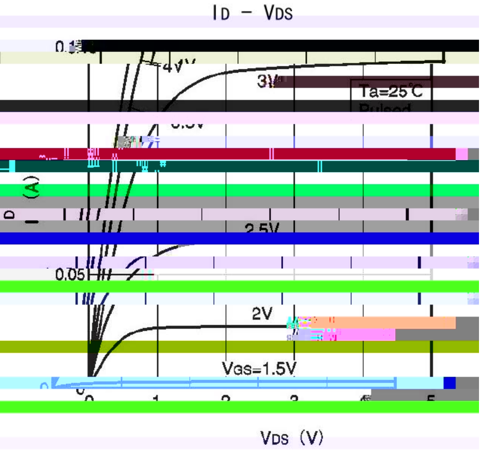
*2:With each pin mounted on the recommended lands

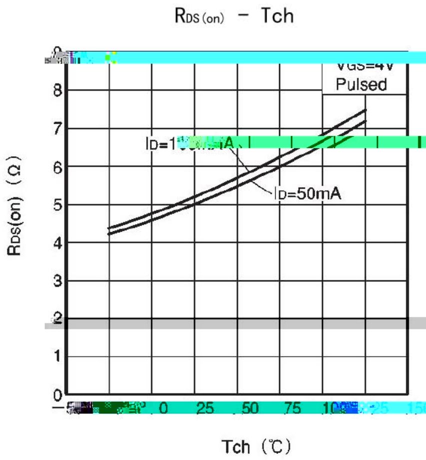
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V I_D=10μA	30			V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=3.0V I_D=100μA	0.8		1.5	V
Static Drain–Source On–Resistance	$R_{DS(on)1}$	V_{GS}=4.0V I_D=10mA		5.0	8.0	Ω
	$R_{DS(on)2}$	V_{GS}=2.5V I_D=1.0mA		7.0	13	Ω
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V V_{GS}=0V			1.0	μA
Gate–Body Leakage.	I_{GSS}	V_{GS}=±20V V_{DS}=0V			±1	μA
Forward Transconductance	g_{FS}	V_{DS}=3V I_D				

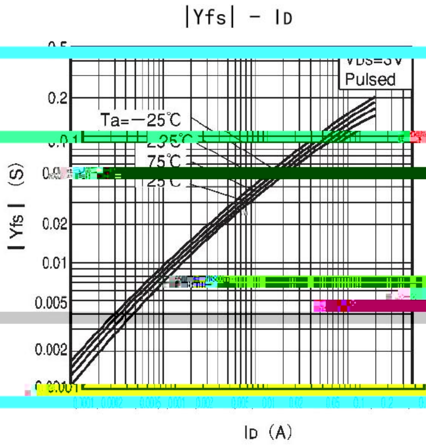
/ Electrical Characteristic Curve

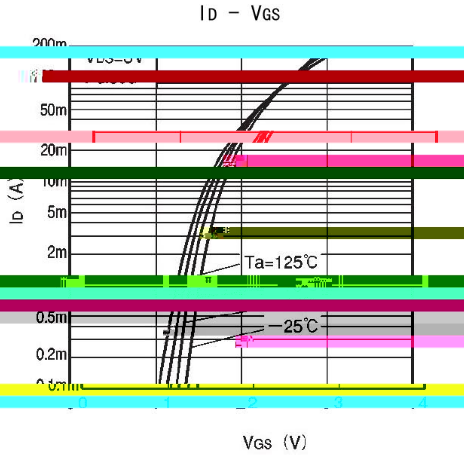


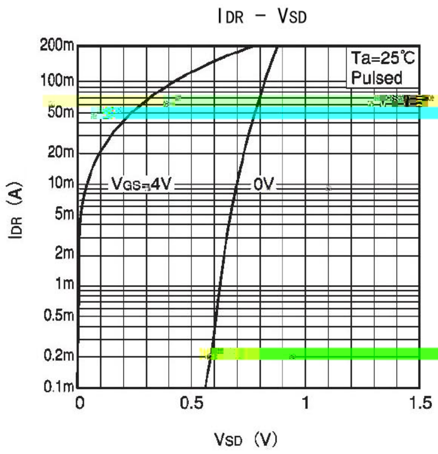


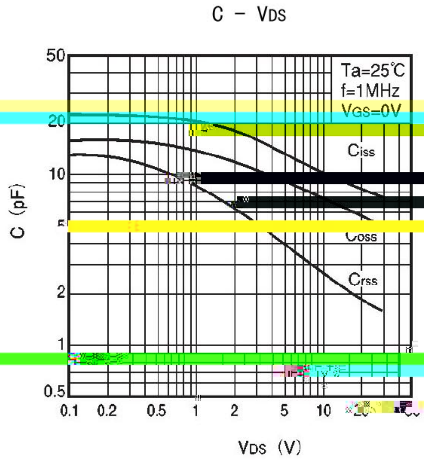


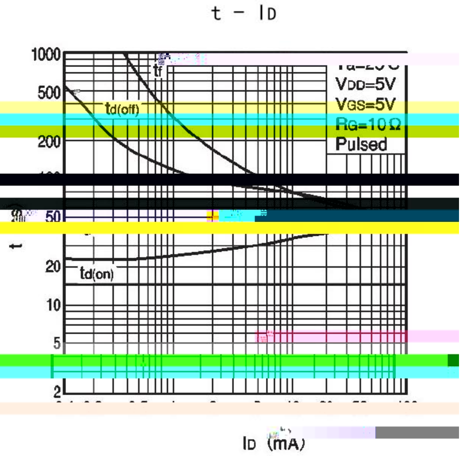




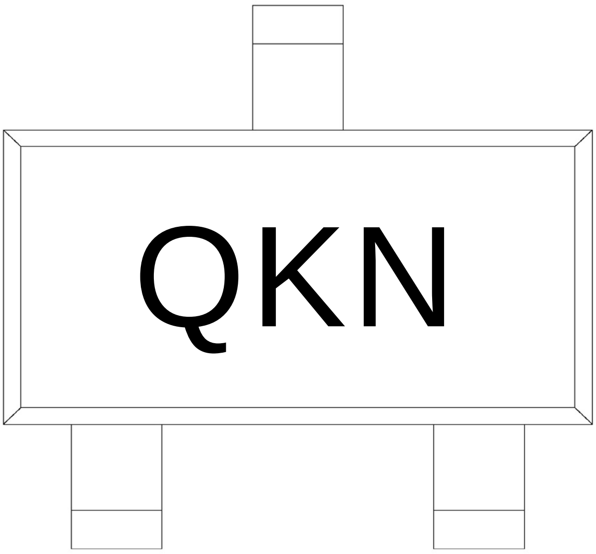








/ Marking Instructions



Q

KN

Note:

Q: Automobile halogen-free product Code

KN: Package type

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

	Note:
1 150 200 60 120sec;	1.Preheating:150~200 , Time:60~120sec.
2 255 5 5 0.5sec;	2.Peak Temp.:255 5 , Duration:5 0.5sec.
3 2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-323	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205